

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|--|------------------|---------|------------------|
| S140 | 37 | ((thermal heat) near (dissipat\$3 sink spreader)) with (wir\$4 near line\$1) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2005/10/06 07:15 |
| S141 | 7 | module AND (packag\$3 substrate) AND terminal\$1 AND ((wir\$3 metal conduct\$3) NEAR line\$1) AND (power NEAR (switch\$3 device\$1 chip\$1 die\$1 transistor\$1)) AND electrode\$1 AND mount\$3 AND ((integrated NEAR circuit) IC) AND ((heat thermal) NEAR (sink dissipat\$3)) AND (electrically NEAR connect\$3) AND (resin seal\$3 encapsulat\$3).CLM. | US-PGPUB; USPAT | OR | ON | 2005/10/06 07:26 |